

LOW-PRESSURE MOLDING

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Elemelt Technical Data Sheet TC-968-0000-W

Elemelt TC-968-0000-W is a high molecular weight copolyester resin designed for low pressure molding. This resin has the characteristics of a short open time with a high melting point. Application temperature is 180-210°C which is ideal for PCB encapsulation and durability. Adhesion can be improved with plasma treating or by coating chemical primer. This product is available in white.

1. TYPICAL SPECIFICATIONS

Appearance	: White pellet solid.
Melting Point(°C)	: 160 ~ 170
Viscosity(dPa·s/220°C)	: 100 ~ 200
Acid Value (mg-KOH/gm)	: 3 Max.
Specific Gravity	: 1.13

2. SHORE-A HARDNESS

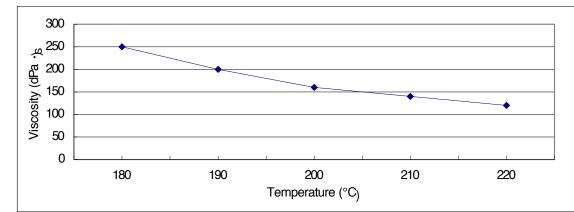
Measured Temperature °C	Shore-A Hardness
23	91
40	90
60	85
80	83
100	75
120	60

3. WATER ABSORBTION

Water Absorbtion(%)

: 0.4(RH23°C 50%,1Day)





4. VISCOSITY CURVE VERSUS TEMPERATURE

5. APPLICATION TEMPERATURE

180°C ~210°C

6. PACKAGING

20 kg net, paper bag.

7. STORAGE CONDITIONS

Store in sealable container once shipping bag has been opened. Copolyesters are sensitive to high humidity and will absorb atmospheric moisture. <u>Be sure to dry polyester resin at 60°C for more than 4 hours before use.</u> Shelf life is 6 months with proper storage and at a temperature below 30°C.

Note:

Our data and recommendations in this sheet do not constitute a warranty or representation for which we assume legal responsibility. They are offered only for your reference, investigation and verification, not guaranteed values.

Before using this product, please check or study carefully, that this grade is suitable for your purpose, application and process condition, etc.